

# 10V Drive Nch MOSFET

## R5019ANJ

### ● Structure

Silicon N-channel MOSFET

### ● Features

- 1) Low on-resistance.
- 2) High-speed switching.
- 3) Wide SOA.
- 4) Drive circuits can be simple.
- 5) Parallel use is easy.

### ● Application

Switching

### ● Packaging specifications

| Type     | Package                      | Taping |
|----------|------------------------------|--------|
|          | Code                         | TL     |
|          | Basic ordering unit (pieces) | 1000   |
| R5019ANJ |                              | ○      |

### ● Absolute maximum ratings (Ta = 25°C)

| Parameter                      |            | Symbol      | Limits      | Unit |
|--------------------------------|------------|-------------|-------------|------|
| Drain-source voltage           |            | $V_{DSS}$   | 500         | V    |
| Gate-source voltage            |            | $V_{GSS}$   | ±30         | V    |
| Drain current                  | Continuous | $I_D$ *3    | ±19         | A    |
|                                | Pulsed     | $I_{DP}$ *1 | ±76         | A    |
| Source current<br>(Body Diode) | Continuous | $I_S$ *3    | 19          | A    |
|                                | Pulsed     | $I_{SP}$ *1 | 76          | A    |
| Avalanche current              |            | $I_{AS}$ *2 | 9.5         | A    |
| Avalanche energy               |            | $E_{AS}$ *2 | 24.3        | mJ   |
| Power dissipation              |            | $P_D$ *4    | 100         | W    |
| Channel temperature            |            | $T_{ch}$    | 150         | °C   |
| Range of storage temperature   |            | $T_{stg}$   | -55 to +150 | °C   |

 \*1  $P_w \leq 10\mu s$ , Duty cycle  $\leq 1\%$ 

 \*2  $L = 500\mu H$ ,  $V_{DD} = 50V$ ,  $R_G = 25\Omega$ ,  $T_{ch} = 25^\circ C$ 

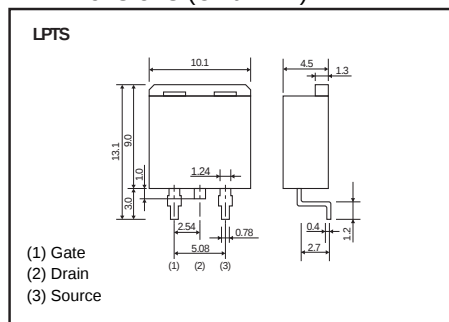
\*3 Limited only by maximum temperature allowed.

 \*4  $T_C = 25^\circ C$ 

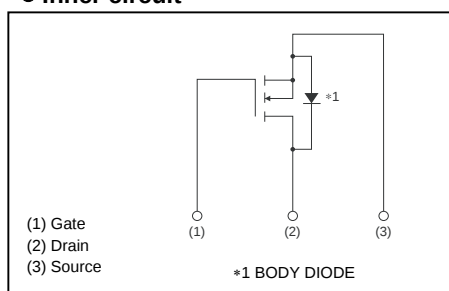
### ● Thermal resistance

| Parameter       | Symbol         | Limits | Unit   |
|-----------------|----------------|--------|--------|
| Channel to Case | $R_{th(ch-c)}$ | 1.25   | °C / W |

### ● Dimensions (Unit : mm)



### ● Inner circuit



## ● Electrical characteristics (Ta = 25°C)

| Parameter                               | Symbol         | Min. | Typ. | Max.      | Unit     | Conditions                         |
|-----------------------------------------|----------------|------|------|-----------|----------|------------------------------------|
| Gate-source leakage                     | $I_{GSS}$      | -    | -    | $\pm 100$ | nA       | $V_{GS} = \pm 30V$ , $V_{DS} = 0V$ |
| Drain-source breakdown voltage          | $V_{(BR)DSS}$  | 500  | -    | -         | V        | $I_D = 1mA$ , $V_{GS} = 0V$        |
| Zero gate voltage drain current         | $I_{DSS}$      | -    | -    | 100       | $\mu A$  | $V_{DS} = 500V$ , $V_{GS} = 0V$    |
| Gate threshold voltage                  | $V_{GS(th)}$   | 2.5  | -    | 4.5       | V        | $V_{DS} = 10V$ , $I_D = 1mA$       |
| Static drain-source on-state resistance | $R_{DS(on)}^*$ | -    | 0.18 | 0.24      | $\Omega$ | $I_D = 9.5A$ , $V_{GS} = 10V$      |
| Forward transfer admittance             | $ Y_{fs} ^*$   | 6.5  | -    | -         | S        | $V_{DS} = 10V$ , $I_D = 9.5A$      |
| Input capacitance                       | $C_{iss}$      | -    | 2050 | -         | pF       | $V_{DS} = 25V$                     |
| Output capacitance                      | $C_{oss}$      | -    | 1200 | -         | pF       | $V_{GS} = 0V$                      |
| Reverse transfer capacitance            | $C_{rss}$      | -    | 50   | -         | pF       | $f = 1MHz$                         |
| Turn-on delay time                      | $t_{d(on)}^*$  | -    | 40   | -         | ns       | $V_{DD} = 250V$ , $I_D = 9.5A$     |
| Rise time                               | $t_r^*$        | -    | 115  | -         | ns       | $V_{GS} = 10V$                     |
| Turn-off delay time                     | $t_{d(off)}^*$ | -    | 165  | -         | ns       | $R_L = 26.3\Omega$                 |
| Fall time                               | $t_f^*$        | -    | 100  | -         | ns       | $R_G = 10\Omega$                   |
| Total gate charge                       | $Q_g^*$        | -    | 55   | -         | nC       | $V_{DD} = 250V$                    |
| Gate-source charge                      | $Q_{gs}^*$     | -    | 11   | -         | nC       | $I_D = 19A$                        |
| Gate-drain charge                       | $Q_{gd}^*$     | -    | 24   | -         | nC       | $V_{GS} = 10V$                     |

\*Pulsed

## ● Body diode characteristics (Source-Drain)

| Parameter       | Symbol     | Min. | Typ. | Max. | Unit | Conditions                  |
|-----------------|------------|------|------|------|------|-----------------------------|
| Forward Voltage | $V_{SD}^*$ | -    | -    | 1.5  | V    | $I_S = 19A$ , $V_{GS} = 0V$ |

\*Pulsed

# ●Electrical characteristic curves

Fig.1 Typical Output Characteristics ( I )

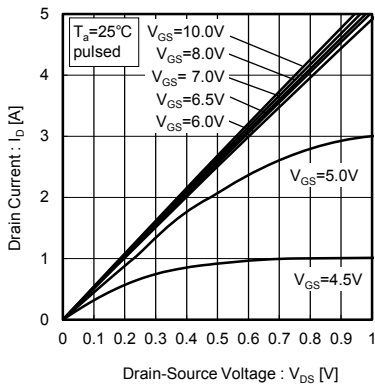


Fig.2 Typical Output Characteristics ( II )

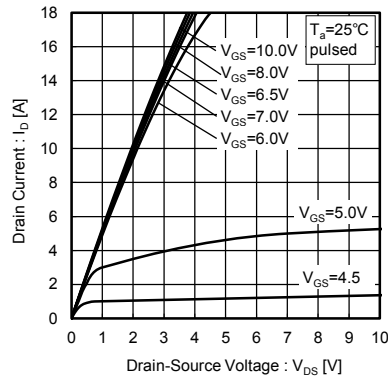


Fig.3 Typical Transfer Characteristics

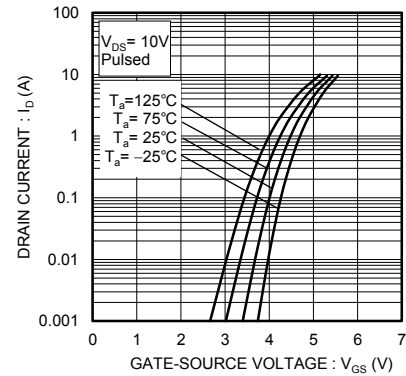


Fig.4 Gate Threshold Voltage vs. Channel Temperature

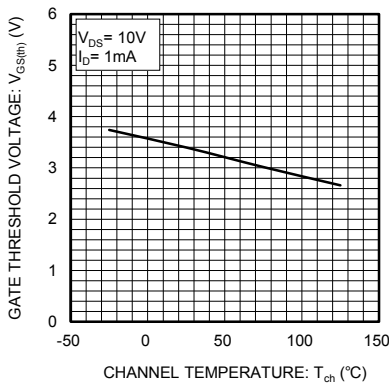


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current

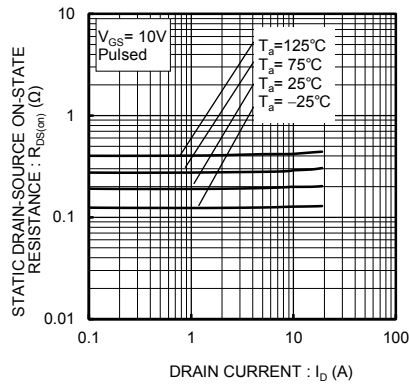


Fig.6 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

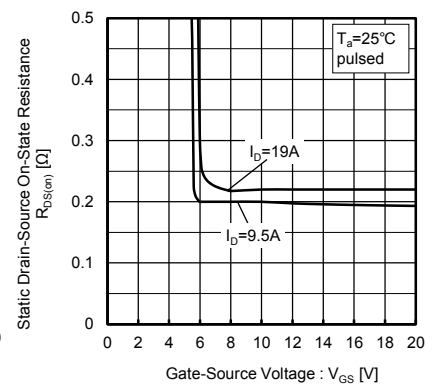


Fig.7 Static Drain-Source On-State Resistance vs. Channel Temperature

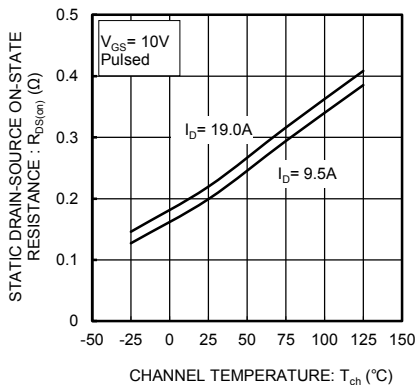


Fig.8 Forward Transfer Admittance vs. Drain Current

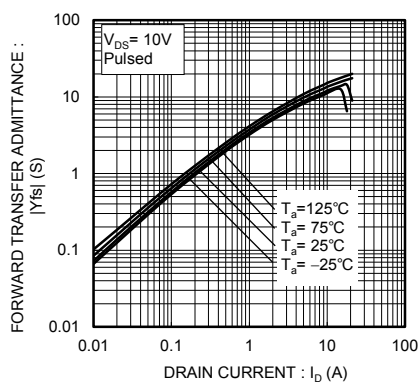


Fig.9 Source Current vs. Source-Drain Voltage

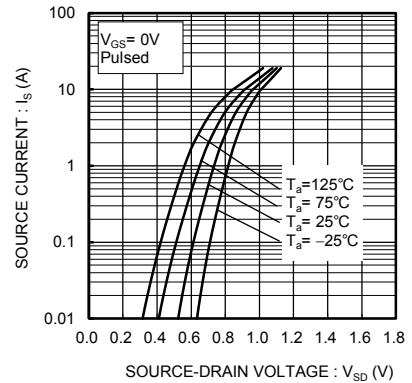


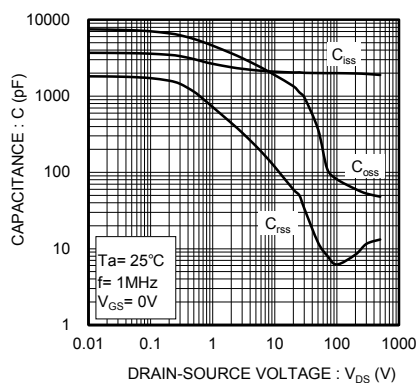
Fig.10 Typical Capacitance vs.  
Drain-Source Voltage

Fig.11 Dynamic Input Characteristics

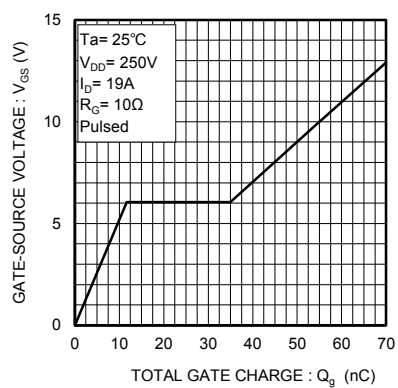
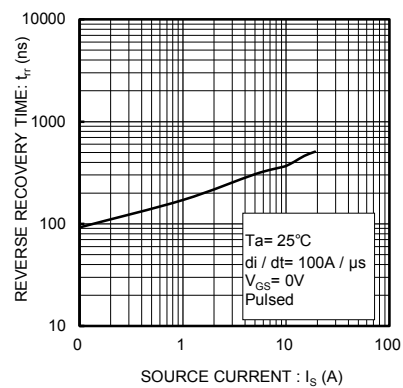
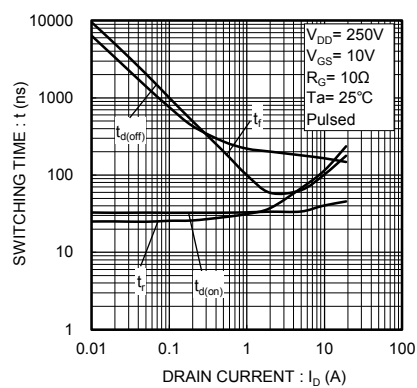
Fig.12 Reverse Recovery Time  
vs. Source Current

Fig.13 Switching Characteristics



## ● Measurement circuits

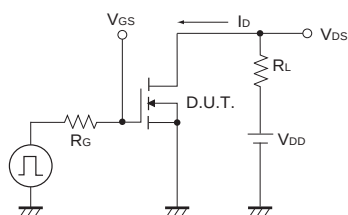


Fig.1-1 Switching Time Measurement Circuit

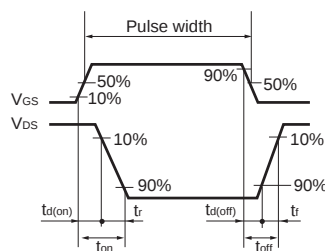


Fig.1-2 Switching Waveforms

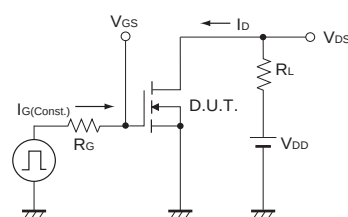


Fig.2-1 Gate Charge Measurement Circuit

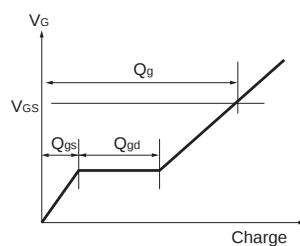


Fig.2-2 Gate Charge Waveform

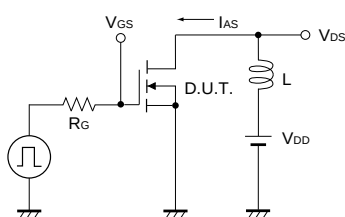


Fig.3-1 Avalanche Measurement Circuit

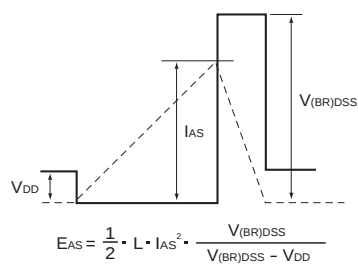


Fig.3-2 Avalanche Waveform

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